CELCON® MC90-HM

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Celcon® MC90-HM is a highly mineral filled and coupled M90 material for producing very flat and dimensionally stable parts (normal flow).

Product information

Resin Identification	POM-MD25	ISO 1043
Part Marking Code	>POM-MD25<	ISO 11469

Rheological properties

Melt mass-flow rate	7	g/10min	ISO 1133
Melt mass-flow rate, Temperature	374	°F	
Melt mass-flow rate, Load	4.76	lb	
Molding shrinkage, parallel	1.5	%	ISO 294-4, 2577
Molding shrinkage, normal	1.3	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	515000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	6500	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	6	%	ISO 527-1/-2
Flexural modulus	508000	psi	ISO 178
Flexural strength	10400	psi	ISO 178
Flexural strain at failure	3.5	%	ISO 178
Compressive stress at 1% strain	4060	psi	ISO 604
Charpy notched impact strength, 23°C	3	ftlb/in^2	ISO 179/1eA
Charpy notched impact strength, -30°C	2.33	ftlb/in^2	ISO 179/1eA
Izod notched impact strength, 23°C	2.9	ftlb/in^2	ISO 180/1A
Poisson's ratio	0.403		

Thermal properties

Melting temperature, 10°C/min	331	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	217	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.33	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	0.5	E-4/°F	ISO 11359-1/-2

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.75	%	Sim. to ISO 62
Density	0.0578	lb/in^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	374	°F
Min. melt temperature	356	°F
Max. melt temperature	392	°F

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Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	$2h^2$-3	s
Back pressure	580	psi

Characteristics

Processing	Injection Molding
Additives	Release agent
Special characteristics	Low Warpage

Additional information

Injection molding

Preprocessing

Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%

Processing

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.

Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

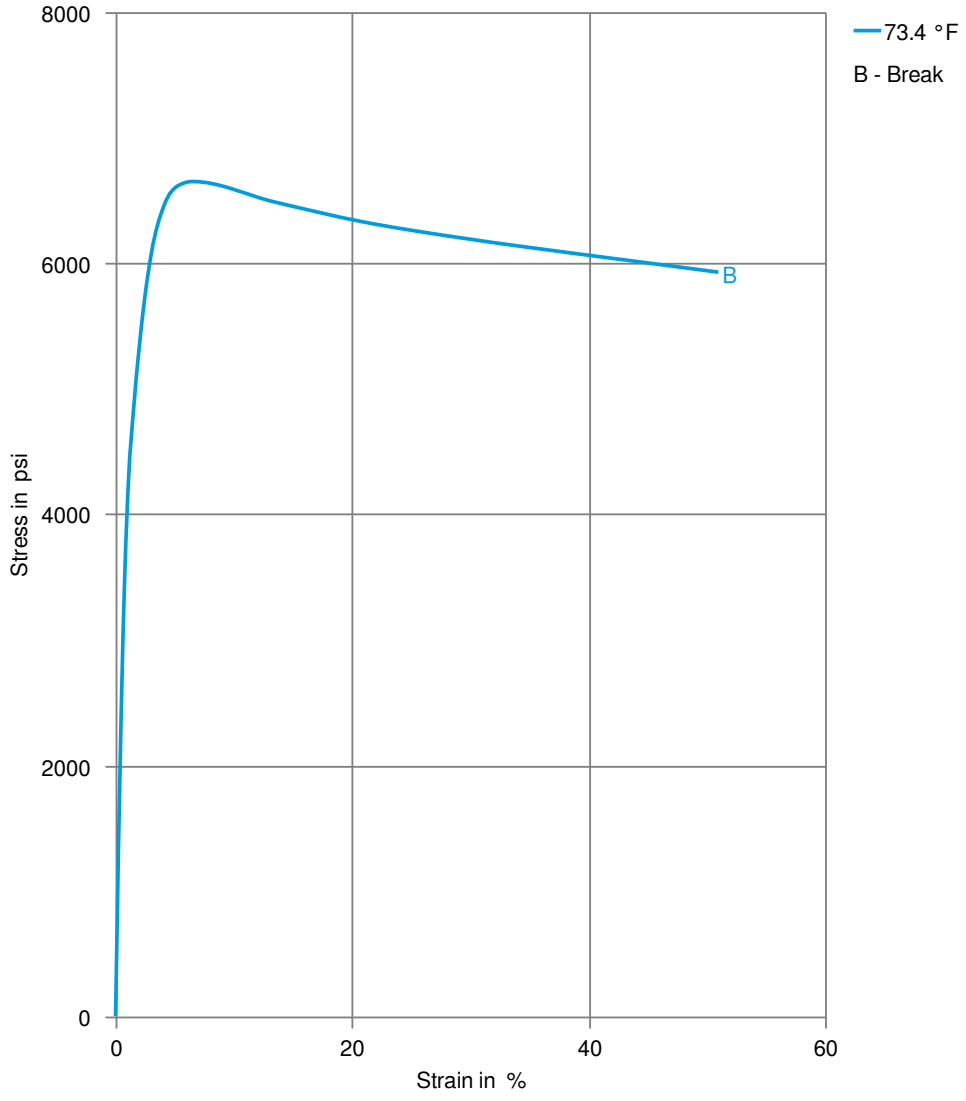
Postprocessing

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Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

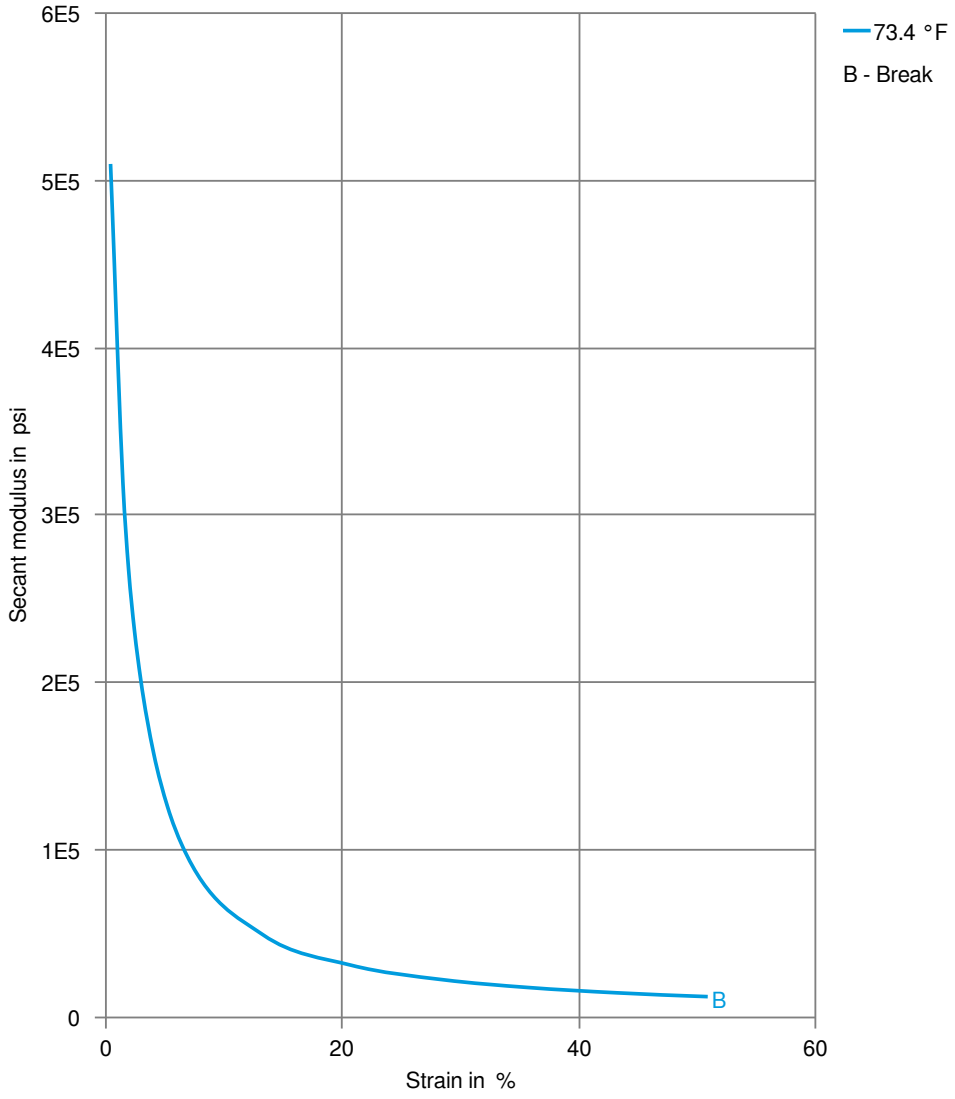
Stress-strain



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Secant modulus-strain



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